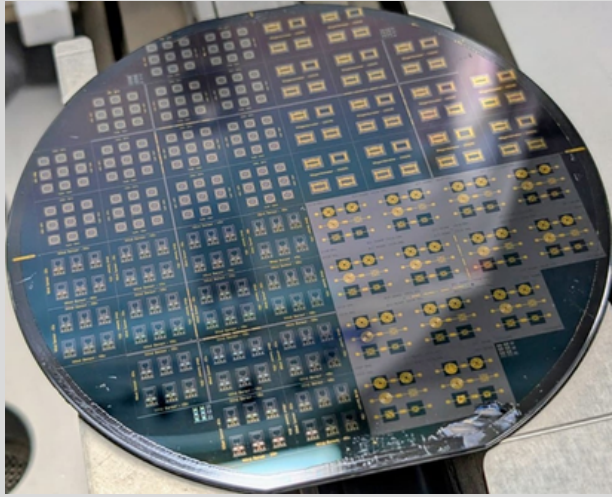


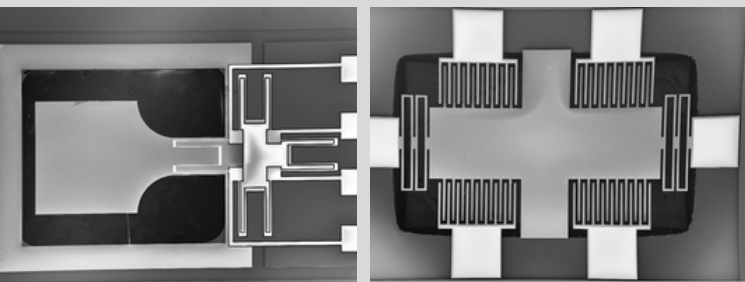


About Us

The SOI-MEMS Multi-Project Wafer (MPW) Fabrication Service at the Centre for Nano Science and Engineering (CeNSE), IISc, provides a cost-effective and time-efficient pathway for prototyping a wide range of MEMS devices. By enabling multiple users to share wafer real estate, the MPW model significantly reduces fabrication cost while maintaining foundry-grade process control and reliability.

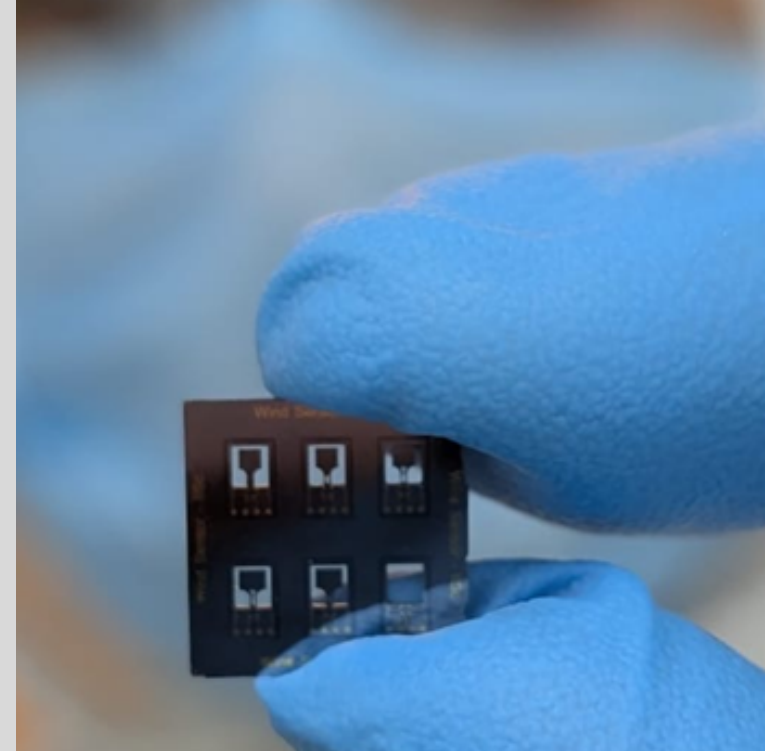
Why Choose Us?

- 1 Lower Prototyping Cost through shared wafer fabrication
- 2 Fast Turnaround (< 12 weeks)
- 3 Standardized, repeatable SOI-MEMS process
- 4 Access to advanced characterization facilities
- 5 Support from experienced MEMS process and design experts



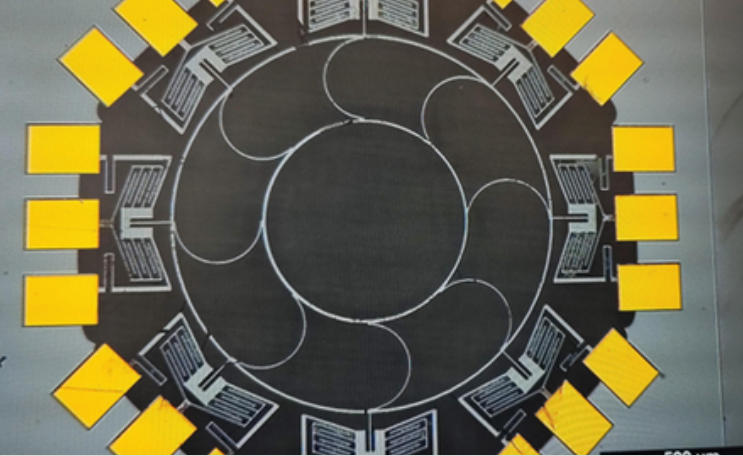
Upcoming MPW Runs

#Run	Design Submission Deadline	Die Shipment
<u>SOI-MEMS</u>		
3	Mar 2026	Jun 2026
4	Jun 2026	Sep 2026
5	Sep 2026	Dec 2026
6	Dec 2026	Mar 2027



**SOI-MEMS
MPW
Service
at CeNSE, IISc**





Standard SOI-MEMS MPW Specifications

- **Chip & Layout** - Standard die size: 11 mm × 11 mm - Active design area: 9 mm × 9 mm
Typical number of designs per die: 5–6 (depending on layout complexity and device design)
- **SOI Wafer Options** - Device layer thickness: 10 μm / 20 μm / 30 μm
- **Process Parameters** - Metallization: Cr/Au - Minimum feature size: 3 μm - Process flow and layer stack: As defined in the CeNSE SOI-MEMS PDK
- All submitted designs must comply with the

Process Flow

The standard SOI-MEMS MPW process flow includes: - Front-side lithography and etching - Device layer patterning - Metallization and contact formation - Backside etching and release

Detailed process steps, layer thicknesses, and mask information are provided as part of the SOI-MEMS PDK.

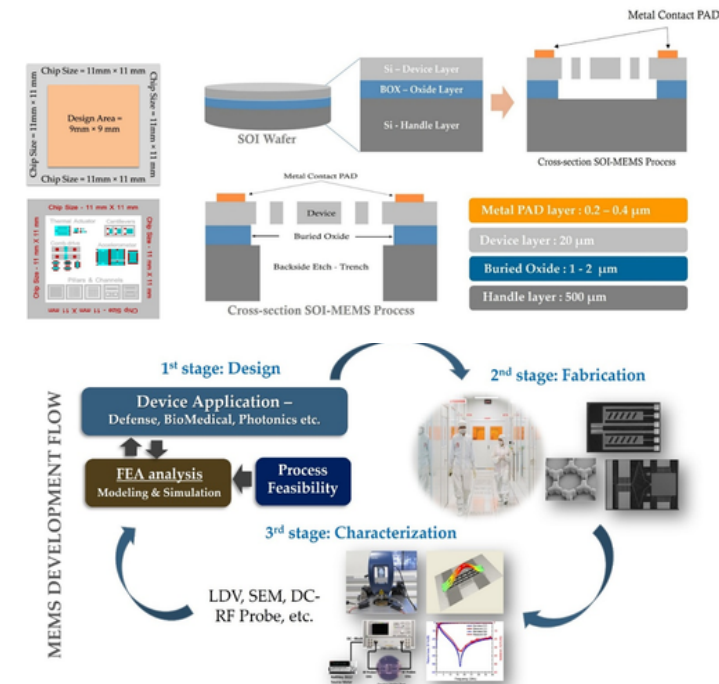
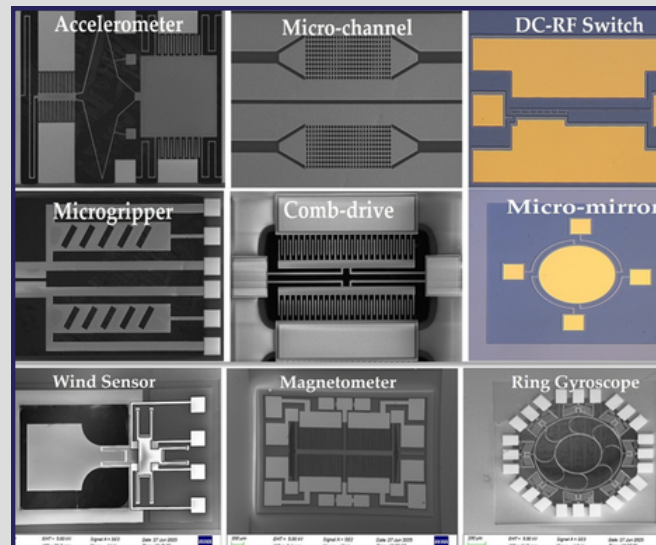
Contact Us

For access to the SOI-MEMS PDK, MPW schedules & technical discussions, write to

- ✉ projects.cense@iisc.ac.in
- ✉ ssudhanshu@iisc.ac.in
- ✉ sabihas@iisc.ac.in

Supported MEMS Devices

- Accelerometers
- Gyroscopes
- Micro-mirrors
- DC-RF MEMS switches
- Optical waveguides
- Resonators and



MEMS Development Support

The MEMS development workflow typically involves three stages:

1. **Design**
2. **Microfabrication**
3. **Characterization**

CeNSE provides technical support at each stage, ensuring smooth translation of designs into functional silicon prototypes.

As part of the MPW service, users are provided access to basic post-fabrication characterization, including: - Scanning Electron Microscopy (SEM) - Laser Doppler Vibrometry (LDV) - Electrical measurements (I-V and C-V)